

A

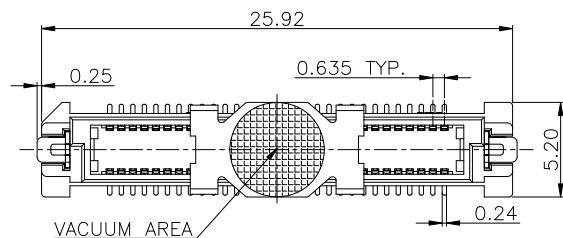
B

C

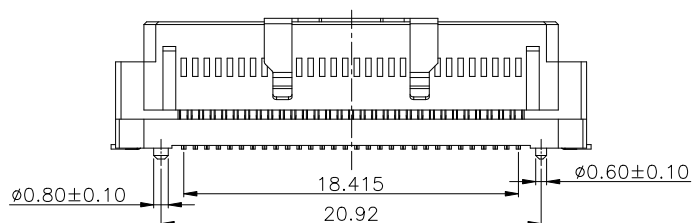
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E

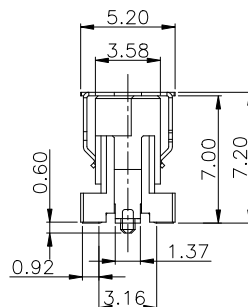
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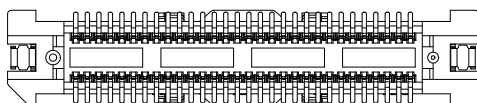
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3



4



1. MATERIAL:
 - 1.1 INSULATOR: LCP, UL 94V-0.
INSULATOR COLOR: SEE ORDER INFORMATION.
 - 1.2 CONTACT: PHOSPHOR BRONZE, SELECTIVE GOLD (SEE ORDER INFORMATION) PLATED IN CONTACT AREA, 40u" MIN TIN PLATED IN SOLDER AREA, 30u" MIN. NICKEL UNDERPLATED OVERALL.
 - 1.3 NAIL: COPPER ALLOY, 40u" MIN TIN PLATED ON SURFACE 30u" MIN. NICKEL UNDERPLATED OVERALL.
 - 1.4 VACUUM COVER: STAINLESS STEEL.
2. SPECIFICATIONS:
 - 2.1 CURRENT RATING: 0.5A.
 - 2.2 CONTACT RESISTANCE: 50mΩ MAX.
 - 2.3 INSULATION RESISTANCE: 1000MΩ MIN.
 - 2.4 DIELECTRIC WITHSTANDING VOLTAGE: AC 250V PER MINUTE.
 - 2.5 OPERATING TEMPERATURE: -40°C~+105°C.
3. NOTES:
 - 3.1 THIS COMPONENT AND ITS HOMOGENEOUS SUBCOMPONENTS ARE RoHS COMPLIANT.
 - 3.2 RESISTANCE TO SOLDERING HEAT: 265°C FOR 10 SECONDS.
4. SOLDER TAIL COPLANARITY 0.10mm Max.

5. ORDER INFORMATION

BB226DB X 2 SX -230E

INSULATOR COLOR: J

A: NATURE

B: BLACK

J: BROWN

CONTACT PLATED:

S1: GOLD FLASH

S2: 3u" GOLD

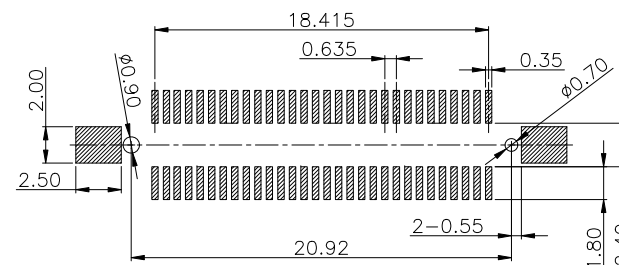
S3: 5u" GOLD

S4: 10u" GOLD

S5: 15u" GOLD

S6: 30u" GOLD

S7: 50u" GOLD



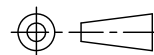
RECOMMENDED PCB LAYOUT(PCB THICKNESS: 1.6mm)
COMPONENT SIDE VIEW(TOLERANCE: ± 0.05)

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REV.	DESCRIPTION	ECN NO.	NAME	DATE
AO	NEW RELEASE		GK	12.13.2012

REVISIONS

DIM.	TOL.
X	
X.X	± 0.30
X.XX	± 0.25
X.XXX	± 0.15
GENERAL ANGLE: $\pm 3^\circ$	



TITLE:

BOARD TO BOARD 60P PITCH 0.635mm MALE SMT VERTICAL TYPE

DWG. NO.:

C-BB226DBX2SX-230E

DRAWN:

GK

PART NO.:

BB226DBX2SX-230E

CHECKED:

Brant

UNIT:

mm

SCALE:

none

SHEET:

1 OF 1

DWG. SIZE:

A4

LAYER:

CA059

APPROVED:

Peter



RFQ NO.:

Q1108061/62

ARTICLE: CPC-CN-002-C